

GS50001B IST COUPON INFORMATION

(With capacitance holes)

This package contains design files for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole and Sequentially Laminated Blind Via Technologies** on a 5.5" (139.7mm) X 0.8" (20.3mm) coupon with a total thickness up to .125 inches and limited to a minimum of 6 layers. This coupon is designed on a small grid, .050" . The maximum hole/pad size is .015" (.38mm) and pad size is .026" (.66mm) for both power and sense circuits); decreasing these feature sizes will not affect the coupon functionality but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

Note: The GS50001B design is limited to a minimum of 4 layer blind vias on either side of the substrate. If it is required to produce 2 layer blind vias, use the GB40001A generic design file.

Note: If this generic design is not suitable to construct a coupon consistent with the actual product, custom coupon design services are available from PWB.

